

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MAURICIO ALEJANDRO LOPEZ CASANOVA	04/11/2019
JOSE CARLOS REMESAR LERA	04/11/2019
SERGIO EDUARDO VERA ARAYA	04/11/2019
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16344221
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ATTORNEY DOCKET NUMBER:	25588-6
NAME OF SUBMITTER:	JASON P. MUELLER
SIGNATURE:	/Jason P. Mueller/
DATE SIGNED:	04/23/2019
Total Attachments: 2	
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ORIGINAL ASSIGNMENT

For valuable consideration, I

Mauricio Alejandro LOPEZ CAZANOVA of Residence Address: Av. Libertador Bernardo O'Higgins 340
Santiago Centro,
Santiago, Chile
8331150

Jose Carlos REMESAR LERA of Residence Address: Av. Libertador Bernardo O'Higgins 340
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Sergio Eduardo VERA ARAYA of Residence Address: Av. Libertador Bernardo O'Higgins 340
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Santiago, Chile
8331150

the below signed joint inventors of record, hereby assign to

PONTIFICIA UNIVERSIDAD CATOLICA DE CHILE

a corporation having an address at

**Av. Libertador Bernardo O'Higgins 340
Santiago-Centro
Santiago, Chile
8331150**

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are the subject of an application for United States Patent signed by me entitled

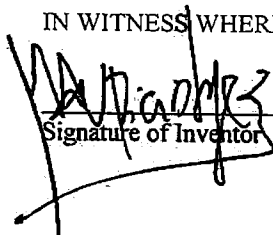
"LIGHTWEIGHT AND/OR THERMALLY INSULATING STRUCTURAL CONCRETES HAVING A HIGHER RESISTANCE/DENSITY AND/OR RESISTANCE/CONDUCTIVITY RATIO, AND METHODS FOR THE PRODUCTION THEREOF"

Application Number:

Date of Filing:

This assignment includes said application, any and all United States and foreign patents, utility models, design registrations, inventor's certificates and other similar rights granted for any of said inventions or improvements, and the right to claim priority, based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes. I hereby authorize the Assignee to apply in all countries in my name, or in its own name, for patents, utility models, design registrations and like rights of exclusion and for inventor's certificates for said inventions and improvements; and I agree for myself and my heirs, legal representatives and assignees, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

IN WITNESS WHEREOF, I hereby set my hand, date of signature and place of signature as indicated below.


Signature of Inventor

Mauricio Alejandro LOPEZ CAZANOVA
Typed Name

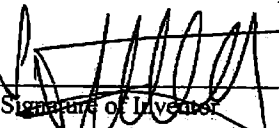
11/04/2019
Date of Signature

SANTIAGO, CHILE
Place of Signature
City, Country

IN WITNESS WHEREOF, I hereby set my hand, date of signature and place of signature as indicated below.


Signature of Inventor Jose Carlos REMESAR LERA 11/04/2019 SANTIAGO CHILE
Typed Name Date of Signature Place of Signature
City, Country

IN WITNESS WHEREOF, I hereby set my hand, date of signature and place of signature as indicated below.


Signature of Inventor Sergio Eduardo VERA ARAYA 11.04.2019 SANTIAGO, CHILE
Typed Name Date of Signature Place of Signature
City, Country